



## SLS20NP04 N-MOSFET and P-MOSFET

### 主要特征/Features

- ◇ Surface Mount T0-252-4L Package ;
- ◇ TrenchFET Power MOSFET;
- ◇ High Power and current handing capability;
- ◇ RoHS compliant / Green EMC;
- ◇ This device is suitable for use as a Battery protection or in other Switching application.

### N-MOSFET

VDS = 40V

ID = 20A

RDS(ON) < 32mΩ @ VGS=10V (Type: 24mΩ)

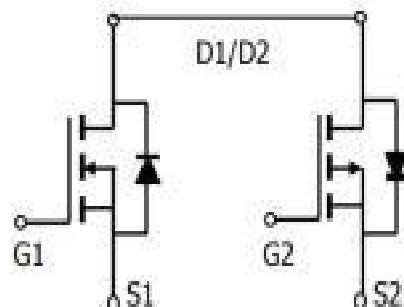
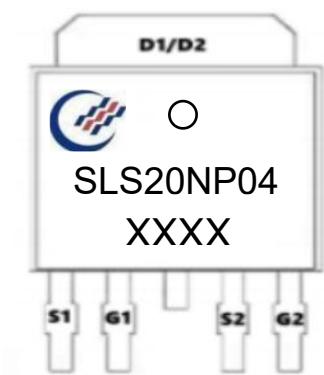
### P-MOSFET

VDS = -40V

ID = -18A

RDS(ON) < 48mΩ @ VGS= -10V (Type: 42mΩ)

### 印字/MARKING 等效电路/Equivalent Circuit





**极限参数/N-MOSFET Absolute Maximum Ratings(TA=25°C unless otherwise noted)**

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
V <sub>DS</sub>	Drain-Source Voltage	40	-40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	20	-18	A
I <sub>D</sub> @T <sub>c</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	15	-16	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	35	-36	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	15	45	mJ
I <sub>AS</sub>	Avalanche Current	10	-10	A
P <sub>D</sub> @T <sub>c</sub> =25°C	Total Power Dissipation <sup>4</sup>	20	25	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	62		°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	5		°C/W

**电性能参数/Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250μA	40	44	---	V
△BVDSS/△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	---	0.032	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =4A	---	24	32	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =3A	---	38	48	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	1.0	1.5	2.5	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-4.5	---	mV/°C
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =4A	---	8	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	2.4	4.8	Ω
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =3A	---	5	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	1.54	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	1.84	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω I <sub>D</sub> =1A	---	7.8	---	ns
T <sub>r</sub>	Rise Time		---	2.1	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	29	---	
T <sub>f</sub>	Fall Time		---	2.1	---	



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**SHENZHEN SLS TECHNOLOGY CO.,LTD.**

**股票代码 871699**

Ciss	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz	---	452	---	pF
Coss	Output Capacitance		---	51	---	
Crss	Reverse Transfer Capacitance		---	38	---	
IS	Continuous Source Current <sub>1,4</sub>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	4.5	A
ISM	Pulsed Source Current <sub>2,4</sub>		---	---	14	A
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C	---	---	1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3、The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=10A
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

**电性能参数/Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-40	---	---	V
△BVDSS/△TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA	---	-0.02	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-5A	---	42	48	mΩ
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-3A	---	48	60	
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-1.6	-2.5	V
△VGS(th)	V <sub>GS(th)</sub> Temperature Coefficient		---	3.72	---	mV/°C
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
Q <sub>g</sub>	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-20V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-6A	---	15.8	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	3.5	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	3.2	---	
Td(on)	Turn-On Delay Time	V <sub>DD</sub> =-15V , V <sub>GS</sub> =-10V , R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-1A	---	5.2	---	ns
T <sub>r</sub>	Rise Time		---	7	---	
Td(off)	Turn-Off Delay Time		---	23	---	
T <sub>f</sub>	Fall Time		---	8	---	

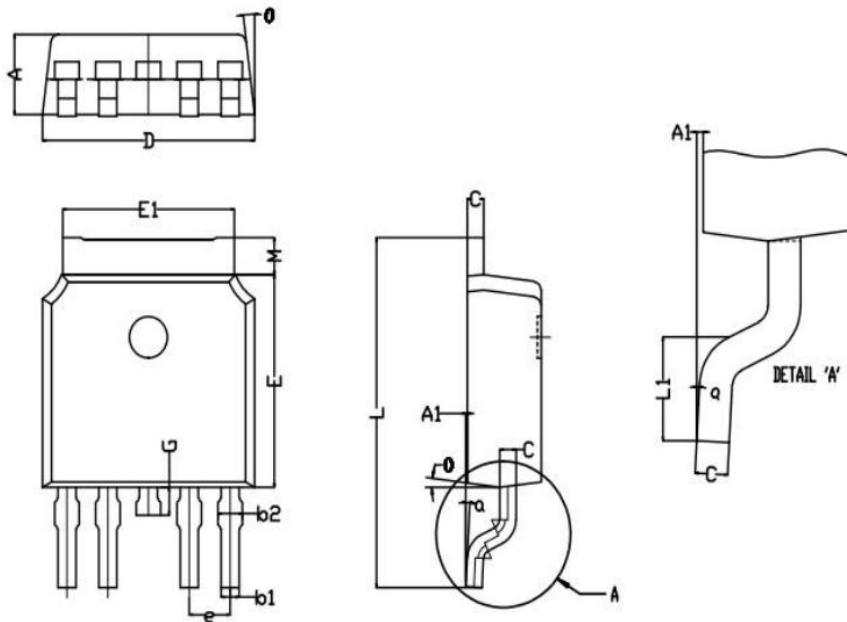


$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$	---	1000	---	pF
$C_{oss}$	Output Capacitance		---	160	---	
$C_{rss}$	Reverse Transfer Capacitance		---	100	---	
$I_s$	Continuous Source Current <sub>1,5</sub>	$V_G=V_D=0V$ , Force Current	---	---	-5.7	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_s=-1A, T_J=25^\circ C$	---	---	-1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  $VDD=-25V, VGS=-10V, L=0.1mH, IAS=-15A$
- 4、The power dissipation is limited by  $150^\circ C$  junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

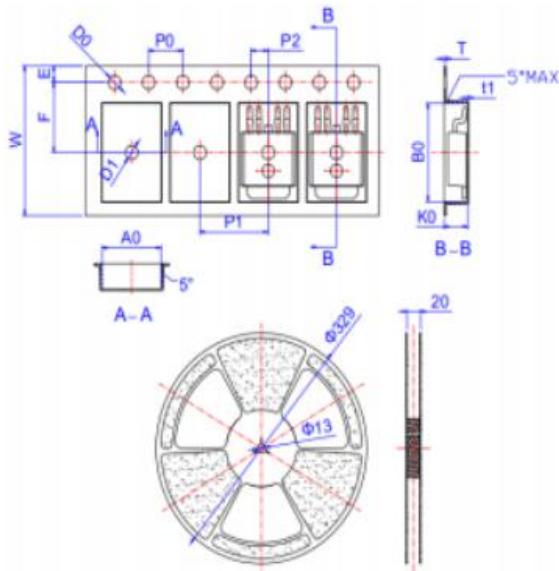
### 成品外观尺寸/Package Mechanical Data:TO-252-4L



Symbol	Dim in mm		
	Min	Nor	Max
A	2.25	2.30	2.35
L1	2.90	3.00	3.10
b1	0.51	0.56	0.61
b2	0.71	0.76	0.81
C	0.46	0.51	0.56
D	6.55	6.60	6.65
e	1.27 (BSC)		
E	6.05	6.10	6.15
E1	5.23	5.33	5.43
L	9.84	10.04	10.24
A1	0.00	0.05	0.10
M	1.01	1.06	1.11
G	0.70	0.80	0.90
O	0°	5°	10°
Q	0°	3°	6°



## 出货规范/Reel Specification-TO-252-4



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
E0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
t	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

Reel	Reel Size	Box	Box Size(mm)	Carton	Carton size(mm)
2500 Pcs	13 inch	2500 Pcs	340×336×29	25 KPcs	353×345×365